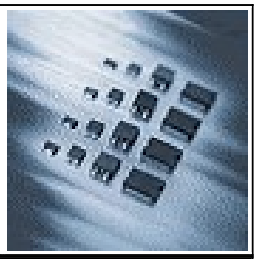
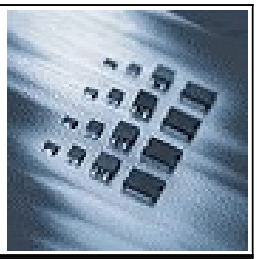


MCDS Collection	
Product	IM06B50GC1
Finish Product Number	MA006083456
Package	PG-MDIP-24-73
Version	126425; 126426;
Calculation date	17. December 2024



Material Content Data Sheet								
Sales Product Name	IM06B50GC1			**Issued**		17. December 2024		
MA#	MA006083456			126425				
Package	PG-MDIP-24-73			**Weight:**		6784.52 mg		
Construction Element	**Material group**	Materials	**CAS if applicable**	**Weight [mg]**	**Average mass [%]**	**Sum [%]**	**Average mass [ppm]**	**Sum [ppm]**
chip_01	inorganic material	silicon	7440-21-3	3.460	0.05	0.05	510	510
chip_02	inorganic material	silicon	7440-21-3	1.067	0.02	0.02	157	157
chip_03	inorganic material	silicon	7440-21-3	1.067	0.02	0.02	157	157
chip_04	inorganic material	silicon	7440-21-3	1.067	0.02	0.02	157	157
chip_05	inorganic material	silicon	7440-21-3	1.067	0.02	0.02	157	157
chip_06	inorganic material	silicon	7440-21-3	1.067	0.02	0.02	157	157
chip_07	inorganic material	silicon	7440-21-3	1.067	0.02	0.02	157	157
chip_08	inorganic material	silicon	7440-21-3	1.855	0.03	0.03	273	273
chip_09	inorganic material	silicon	7440-21-3	1.855	0.03	0.03	273	273
chip_10	inorganic material	silicon	7440-21-3	1.855	0.03	0.03	273	273
chip_11	inorganic material	silicon	7440-21-3	1.855	0.03	0.03	273	273
chip_12	inorganic material	silicon	7440-21-3	1.855	0.03	0.03	273	273
chip_13	inorganic material	silicon	7440-21-3	1.855	0.03	0.03	273	273
leadframe	inorganic material	phosphorus	7723-14-0	0.370	0.01		55	
	non noble metal	iron	7439-89-6	1.233	0.02		182	
	non noble metal	copper	7440-50-8	1231.749	18.16	18.19	181554	181791
wire	noble metal	gold	7440-57-5	0.583	0.01		86	
	non noble metal	aluminium	7429-90-5	56.488	0.83	0.84	8326	8412
encapsulation	organic material	carbon black	1333-86-4	27.702	0.41		4083	
	plastics	epoxy resin	-	346.278	5.10		51040	
	inorganic material	silicondioxide	60676-86-0	3088.801	45.47	50.98	455272	510395
leadfinish	non noble metal	tin	7440-31-5	42.571	0.63	0.63	6275	6275
plating	non noble metal	nickel	7440-02-0	7.676	0.11	0.11	1131	1131
glue	plastics	acrylic resin	-	0.165			24	
	plastics	maleimide resin	-	0.165			24	
	noble metal	silver	7440-22-4	0.494	0.01		73	
	inorganic material	silicondioxide	60676-86-0	0.953	0.01		141	
	plastics	epoxy resin	-	1.430	0.02	0.04	211	473
smd	inorganic material	silicondioxide	60676-86-0	0.002			1	
	noble metal	gold	7440-57-5	0.008			1	
	noble metal	palladium	7440-05-3	0.013			2	

	organic material	ethyl cellulose	9004-57-3	0.016			2	
	noble metal	silver	7440-22-4	0.021			3	
	organic material	DEGBE	112-34-5	0.071			11	
	inorganic material	cobalt(II)oxide	1307-96-6	0.136			20	
	inorganic material	copperoxide	1317-38-0	0.390	0.01		57	
	inorganic material	manganesedioxide	1313-13-9	0.446	0.01	0.02	66	163
pcb metal	non noble metal	copper	7440-50-8	21.465	0.32	0.32	3164	3164
pcb plastic	miscellaneous	miscellaneous	-	26.372	0.39		3887	
	inorganic material	silicondioxide	60676-86-0	42.196	0.62		6219	
	organic material	Poly[phenylglycidylether-coformaldehyde]	28064-14-4	50.108	0.74		7386	
	inorganic material	glass fibre	-	145.049	2.14	3.89	21379	38871
pcb plating	noble metal	gold	7440-57-5	0.067			10	
	non noble metal	nickel	7440-02-0	3.036	0.04	0.04	448	458
dcb ceramic	inorganic material	zirconium dioxide	1314-23-4	5.122	0.08		755	
	inorganic material	aluminum nitride	24304-00-5	454.293	6.70	6.78	66960	67715
dcb metal	non noble metal	copper	7440-50-8	1208.058	17.81	17.81	178062	178062
deviation	< 10%				Sum in total:	100.00		1000000



Material Content Data Sheet								
Sales Product Name	IM06B50GC1			**Issued**		17. December 2024		
MA#	MA006083456			126426				
Package	PG-MDIP-24-73			**Weight:**		6760.65 mg		
Construction Element	**Material group**	Materials	**CAS if applicable**	**Weight [mg]**	**Average mass [%]**	**Sum [%]**	**Average mass [ppm]**	**Sum [ppm]**
chip_01	inorganic material	silicon	7440-21-3	3.460	0.05	0.05	512	512
chip_02	inorganic material	silicon	7440-21-3	1.067	0.02	0.02	158	158
chip_03	inorganic material	silicon	7440-21-3	1.067	0.02	0.02	158	158
chip_04	inorganic material	silicon	7440-21-3	1.067	0.02	0.02	158	158
chip_05	inorganic material	silicon	7440-21-3	1.067	0.02	0.02	158	158
chip_06	inorganic material	silicon	7440-21-3	1.067	0.02	0.02	158	158
chip_07	inorganic material	silicon	7440-21-3	1.067	0.02	0.02	158	158
chip_08	inorganic material	silicon	7440-21-3	1.855	0.03	0.03	274	274
chip_09	inorganic material	silicon	7440-21-3	1.855	0.03	0.03	274	274
chip_10	inorganic material	silicon	7440-21-3	1.855	0.03	0.03	274	274
chip_11	inorganic material	silicon	7440-21-3	1.855	0.03	0.03	274	274
chip_12	inorganic material	silicon	7440-21-3	1.855	0.03	0.03	274	274
chip_13	inorganic material	silicon	7440-21-3	1.855	0.03	0.03	274	274
leadframe	inorganic material	phosphorus	7723-14-0	0.370	0.01		55	
	non noble metal	iron	7439-89-6	1.233	0.02		182	
	non noble metal	copper	7440-50-8	1231.749	18.22	18.25	182194	182431
wire	noble metal	gold	7440-57-5	0.583	0.01		86	
	non noble metal	aluminium	7429-90-5	56.488	0.84	0.85	8355	8441
encapsulation	organic material	carbon black	1333-86-4	27.702	0.41		4098	
	plastics	epoxy resin	-	346.278	5.12		51220	
	inorganic material	silicondioxide	60676-86-0	3088.801	45.63	51.16	456880	512198
leadfinish	non noble metal	tin	7440-31-5	42.571	0.63	0.63	6297	6297
plating	non noble metal	nickel	7440-02-0	7.676	0.11	0.11	1135	1135
solder	non noble metal	antimony	7440-36-0	0.902	0.01		133	
	noble metal	silver	7440-22-4	2.256	0.03		334	
	non noble metal	tin	7440-31-5	5.866	0.09	0.13	868	1335
glue	plastics	acrylic resin	-	0.165			24	
	plastics	maleimide resin	-	0.165			24	
	inorganic material	silicondioxide	60676-86-0	0.352	0.01		52	
	noble metal	silver	7440-22-4	0.494	0.01		73	
	plastics	epoxy resin	-	0.528	0.01	0.03	78	251
smd	inorganic material	silicondioxide	60676-86-0	0.002			1	
	noble metal	gold	7440-57-5	0.008			1	
	noble metal	palladium	7440-05-3	0.013			2	
	organic material	ethyl cellulose	9004-57-3	0.016			2	
	noble metal	silver	7440-22-4	0.021			3	
	organic material	DEGBE	112-34-5	0.071			11	
	inorganic material	cobalt(II)oxide	1307-96-6	0.136			20	
	inorganic material	copperoxide	1317-38-0	0.390	0.01		58	
	inorganic material	manganesedioxide	1313-13-9	0.446	0.01	0.02	66	164
pcb metal	non noble metal	copper	7440-50-8	21.465	0.32	0.32	3175	3175
pcb plastic	plastics	epoxy resin	-	104.548	1.55		15464	
	inorganic material	glass fibre wool	65997-17-3	127.781	1.89	3.44	18901	34365
pcb plating	noble metal	gold	7440-57-5	0.067			10	
	non noble metal	nickel	7440-02-0	3.036	0.04	0.04	449	459

dcb ceramic	inorganic material	zirconium dioxide	1314-23-4	5.122	0.08		758	
	inorganic material	aluminum nitride	24304-00-5	454.293	6.72	6.80	67197	67955
dcb metal	non noble metal	copper	7440-50-8	1208.058	17.87	17.87	178690	178690
deviation	< 10%				Sum in total:	100.00		1000000

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